



nRad

Research and Development System for High Performance Slot Die Coating



Prove Your Process on a Truly Scalable Platform

- Highly efficient material utilization with minimal waste
- Patented slot-die based deposition technology
- Coating thickness range from 20nm to 100 μm
- Uniformities of ±3% and edge effect of less than 5mm achievable
- Coating technology proven scalable to large area processing

Supports a Variety of Substrates:

- Rigid or Flexible
- Glass
- Plastic
- Metal Foils
- Silicon Wafers

Perfect for Many Applications

- Flat Panel Displays
- OLED's
- Photovoltaics (Thin Film and Si)
- Flexible Electronics
- Optical Films

Unmatched Performance & Value in an R&D System

FEATURES

- Patented technology and proprietary design provide reliable performance in a small package
- Simple yet flexible design and operation, capable of depositing a wide range of materials for a variety of applications
- Compact system is compatible with most standard glove boxes and laboratory benchtops
- Fully automated coating process controlled through recipe programmable parameters
- Linear servomotor driven air bearing stage assures smooth operation and accurate coating
- User friendly controls with on board touch screen and PC based software
- Extremely low fill volumes ideal for testing small samples of material
- Programmable coating gap (micron resolution), measured and adjusted for every substrate processed.
- Programmable priming step to establish coating bead immediately prior to deposition on the substrate

PROCESS ADVANTAGES

- Slot die coating technology maximizes coating fluid utilization without the waste associated with alternative methods
- Efficient use of materials minimizes environmental impact and disposal costs
- Process is suitable for development applications and scalable to larger production sizes
- Process can also be adapted to a roll to roll platform
- Precise, programmable control of coating gap and die motion profile provides highly uniform coatings and excellent control of coating edge profiles
- Effective adjustable coating speed 0-2m/min

OPTIONS

- Full atmospheric or inert isolation to allow processing in low oxygen/low moisture environment
- Vacuum chucks are available for a wide variety of substrates, including display glass and flexible plastic film as well as silicon PV wafers
- Independent temperature control of process material and substrate (replace existing bullet)
- Slot dies manufactured out of various alloys for processing with corrosive materials.
- Substrate lift mechanism for Robotic load/unload.

SYSTEM SPECIFICATION

Substrate Size	Standard 150 mm ²
	Maximum 210 x 300 mm
	150 or 200mm wafer option
Substrate Type	Glass, plastic, metal foils, silicon wafers
	Rigid or Flexible
Substrate Thickness	Rigid: 0.5 to 6mm
	Flexible: > 100μm
Coating Thickness Range	20nm to 100 μm (dry)
	(depending on material & system options)
Coating Uniformity*	± 3% or better for films over 150nm
	± 5% or better for films 50 and 150nm
Leading/Trailing Edge Effect*	5-10 mm or better
Coating Material Viscosity	Standard 1 to 70 cP
Range	Upto10,000cPwithhighviscositypump
System Fill Volume*	As low under 10 ml
System Dimensions	L: 911mm W: 578mm H: 645mm
	170 kg / 380lbs
Certification	UL & CE Compliant

^{*}Performance achievable with materials optimized for slot die coating. This metric is highly material dependent





